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APPLICATION N	O. F	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/748,271		12/31/2003	Do-young Kim	249/430 6611	
	7590 04/29/2005			EXAMINER	
	TERBA, P	C.C.	NGUYEN, JOSEPH H		
SUITE 2000 1101 WILSON BOULEVARD				ART UNIT	PAPER NUMBER
ARLINGTON, VA 22209				2815	
				DATE MAILED: 04/29/2005	

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)	AN				
	10/748,271	KIM ET AL.	00.				
Office Action Summary	Examiner	Art Unit					
	Joseph Nguyen	2815					
The MAILING DATE of this communication appeared for Reply	pears on the cover shee	t with the correspondence addr	ess				
A SHORTENED STATUTORY PERIOD FOR REPL THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.1 after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a repl - If NO period for reply is specified above, the maximum statutory period - Failure to reply within the set or extended period for reply will, by statute Any reply received by the Office later than three months after the mailin earned patent term adjustment. See 37 CFR 1.704(b).	I36(a). In no event, however, ma ly within the statutory minimum of will apply and will expire SIX (6) for cause the application to becom	y a reply be timely filed thirty (30) days will be considered timely. MONTHS from the mailing date of this come e ABANDONED (35 U.S.C. § 133).	munication.				
Status							
1) Responsive to communication(s) filed on 24 N	Narch 2005.						
:	s action is non-final.						
•	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.						
Disposition of Claims							
 4) Claim(s) 1-66 is/are pending in the application 4a) Of the above claim(s) 20-66 is/are withdray 5) Claim(s) is/are allowed. 6) Claim(s) 1-19 is/are rejected. 7) Claim(s) is/are objected to. 8) Claim(s) are subject to restriction and/or 	wn from consideration.						
Application Papers							
9) The specification is objected to by the Examine 10) The drawing(s) filed on 31 December 2003 is/a Applicant may not request that any objection to the Replacement drawing sheet(s) including the correct 11) The oath or declaration is objected to by the Examine 11.	are: a)⊠ accepted or b drawing(s) be held in abe tion is required if the draw	yance. See 37 CFR 1.85(a). ring(s) is objected to. See 37 CFR	1.121(d).				
Priority under 35 U.S.C. § 119		•					
12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of: 1. Certified copies of the priority document 2. Certified copies of the priority document 3. Copies of the certified copies of the priority application from the International Burea * See the attached detailed Office action for a list	ts have been received. ts have been received i ority documents have be u (PCT Rule 17.2(a)).	n Application No een received in this National St	tage				
Attachment(s) 1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date 3/3/05, 6/21/04.	Paper	ew Summary (PTO-413) No(s)/Mail Date of Informal Patent Application (PTO-1	52)				

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DETAILED ACTION

Election/Restrictions

Applicant's election of claims 1-19 in the reply filed on 3/24/2005 is acknowledged. Because applicant did not distinctly and specifically point out the supposed errors in the restriction requirement, the election has been treated as an election without traverse (MPEP § 818.03(a)).

Claim Rejections - 35 USC § 112

The following is a quotation of the second paragraph of 35 U.S.C. 112:

The specification shall conclude with one or more claims particularly pointing out and distinctly claiming the subject matter which the applicant regards as his invention.

Claims 3, 5, 12 and 14 are rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.

Regarding claims 3 and 12, it is not understood what type of hardness is claimed (i.e. Rockwell hardness, Vickers hardness...) since applicant does not disclose the hardness measuring method is being used. Therefore, it must be corrected to include a type of hardness of the protective cap.

Regarding claims 5 and 14, it is not understood how "the protective cap is formed on an upper surface of the semiconductor chip and *between* the semiconductor chip and the flexible substrate" is obtained since in figure 2 of the instant application, it

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appears that the protective cap is formed on an upper surface of the semiconductor chip but not between the semiconductor chip and the flexible substrate.

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

Claims 1, 4-8, 10, 13-17 and 19 are rejected under 35 U.S.C. 102(e) as being anticipated by Koyama (US 2001/0017372 A1).

Regarding claim 1, Koyama discloses on figure 5 a thin film semiconductor comprising a flexible substrate 501 (para [0065], lines 3-5); a semiconductor chip 601 (para [0069], lines 1-3), which is formed on the flexible substrate; and a protective cap 518 (para [0072], lines 4-7), which seals the semiconductor chip.

Note that Koyama teaches that the substrate 501 is a plastic substrate (para [0065], lines 3-5), which is the same material being used to form the *flexible* substrate in the instant application (page 18, lines 2-3 of the instant application). Therefore, the substrate 501 is flexible. Further, the term "protective" is merely a label. Element 518 is considered "protective layer" since it constitutes a similar structure and function as the claimed protective cap.

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Regarding claim 4, Koyama discloses on figure 5 the protective cap 518 is formed on an upper surface of the semiconductor device.

Regarding claim 5, as best understood, Koyama discloses on figure 5 the protective cap 518 is formed on an upper surface of the semiconductor chip 601 and between the semiconductor chip 601 and the flexible substrate 501.

Regarding claim 6, Koyama discloses on figure 5 the semiconductor chip 601 is a thin film transistor (para [0069], lines 1-3).

Regarding claim 7, Koyama discloses on figure 5 the protective cap 518 is formed of an ultraviolet curing resin (para [0072], lines 4-7). Applicant discloses that the ultraviolet curing resin is an acrylic resin (para [0026] of the instant application]). Koyama teaches that the protective cap is formed of an acrylic resin (para [0072], lines 4-7). Therefore, Koyama teaches the protective cap is an ultraviolet curing resin.

Regarding claim 8, Koyama discloses that the flexible substrate is formed of plastic (para [0065], lines 3-5).

Regarding claim 10, Koyama discloses on figure 5 an electronic device including a flexible substrate 501 and a semiconductor chip 601, the electronic device comprising a protective cap 518 that seals the semiconductor chip.

Regarding claim 13, Koyama discloses on figure 5 the protective cap 518 is formed on an upper surface of the semiconductor chip 601.

Regarding claim 14, as best understood, Koyama discloses on figure 5 the protective cap 518 is formed on an upper surface of the semiconductor chip 601 and between the semiconductor chip 601 and the flexible substrate 501.

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Regarding claim 15, Koyama discloses on figure 5 the semiconductor chip 601 is a thin film transistor (para [0069], lines 1-3).

Regarding claim 16, Koyama discloses on figure 5 the protective cap 518 is formed of an ultraviolet curing resin (para [0072], lines 4-7). Applicant discloses that the ultraviolet curing resin is an acrylic resin (para [0026] of the instant application]). Koyama teaches that the protective cap is formed of an acrylic resin (para [0072], lines 4-7). Therefore, Koyama teaches the protective cap is an ultraviolet curing resin.

Regarding claim 17, Koyama discloses that the flexible substrate is formed of plastic (para [0065], lines 3-5).

Regarding claim 19, Koyama discloses on figure 9C further an organic light emitting diode connected to the semiconductor chip (para [0098], [0099]).

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 2 and 11 are rejected under 35 U.S.C. 103(a) as being unpatentable over Kovama.

Regarding claims 2 and 11, the difference between Koyama and the claimed invention is the tensile strength of the protective cap being greater than about 30 GPa. However, it would have been obvious to one of ordinary skill in the art at the time the

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invention was made to modify Koyama by having the tensile strength of the protective cap being greater than about 30 GPa for the purpose of providing a better protection of a semiconductor device, since it has been held that where the general conditions of a claim are disclosed in the prior art discovering the optimum or working ranges involves only routine skill in the art. In re Aller, 105 USPQ 233.

Claims 9 and 18 are rejected under 35 U.S.C. 103(a) as being unpatentable over Koyama, and further in view of Yamada et al. (US 2002/0097362 A1)

Regarding claims 9 and 18, the difference between Koyama and the claimed invention is the flexible substrate being a glass substrate having a thickness less than about 100 µm. However, Yamada et al. teaches a glass substrate having thickness being less than about 100 µm (para [0215], lines 4-5). In view of such teaching, it would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Koyama by having a glass substrate having a thickness less than about 100 µm for the purpose of manufacturing a semiconductor device in a cost effective way since the thinner the substrate, the cheaper it is to form the semiconductor device.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Joseph Nguyen whose telephone number is (571) 272-1734. The examiner can normally be reached on Monday-Friday, 7:30 am- 4:30 pm. If attempts to reach the examiner by telephone are unsuccessful, the examiner's

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the organization where this application or proceeding is assigned is (703) 872-9306 for

supervisor, Tom Thomas can be reached on (571) 272-1664. The fax phone number for

regular communications.

Information regarding the status of an application may be obtained from the

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JN April 26, 2005

TOWTHOMAS
CUREDIASORY PATENT EXAMINER